Product / Package Information

Package	MSOP_EP - GaAs
Body Size	
Lead Count	8
Terminal Finish	100Sn
MS Number	

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.52 E-03	87.70	877000	41.83	418280
Thermosets	Epoxy Resin	Proprietary	4.86 E-04	5.00	50000	2.38	23847
Thermosets	Phenol Resin	Proprietary	4.86 E-04	5.00	50000	2.38	23847
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.94 E-04	2.00	20000	0.95	9539
Other inorganic materials	Carbon Black	1333-86-4	2.92 E-05	0.30	3000	0.14	1431
Subtotal			9.72 E-03	100.00	1000000	47.69	476944

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.20 E-03	97.50	975000	40.24	402380
Copper & its alloys	Iron	7439-89-6	1.98 E-04	2.35	23500	0.97	9698
Copper & its alloys	Zinc	7440-66-6	1.01 E-05	0.12	1200	0.05	495
Copper & its alloys	Phosphorus	7723-14-0	2.52 E-06	0.03	300	0.01	124
Subtotal			8.41 E-03	100.00	1000000	41.27	412697

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.07 E-04	100.00	1000000	3.47	34676

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.77 E-04	99.99	1000000	0.87	8687

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	6.89 E-04	100.0	1000000	3.38	33817

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.29 E-04	93.00	930000	3.09	30856
Other organic materials	Gamma Butyrolactone	96-48-0	4.73 E-05	7.00	70000	0.23	2323
Subtotal			6.76 E-04	100.00	1000000	3.32	33179

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.04 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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ADI Proprietary

Product / Package Information

Package	MSOP_EP - GaAs
Body Size	
Lead Count	8
Terminal Finish	SnPb
MS Number	

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	8.52 E-03	87.70	877000	41.83	418280
Thermosets	Epoxy Resin	Proprietary	4.86 E-04	5.00	50000	2.38	23847
Thermosets	Phenol Resin	Proprietary	4.86 E-04	5.00	50000	2.38	23847
Thermosets	Epoxy Cresol Novolac	29690-82-2	1.94 E-04	2.00	20000	0.95	9539
Other inorganic materials	Carbon Black	1333-86-4	2.92 E-05	0.30	3000	0.14	1431
Subtotal			9.72 E-03	100.00	1000000	47.69	476944

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.20 E-03	97.50	975000	40.24	402380
Copper & its alloys	Iron	7439-89-6	1.98 E-04	2.35	23500	0.97	9698
Copper & its alloys	Zinc	7440-66-6	1.01 E-05	0.12	1200	0.05	495
Copper & its alloys	Phosphorus	7723-14-0	2.52 E-06	0.03	300	0.01	124
Subtotal			8.41 E-03	100.00	1000000	41.27	412697

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.01 E-04	85.00	850000	2.95	29474
Tin & its alloys	Lead	7439-92-1	1.06 E-04	15.00	150000	0.52	5201
Subtotal			7.07 E-04	100.00	1000000	3.47	34676

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.77 E-04	99.99	1000000	0.87	8687

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	6.89 E-04	100.0	1000000	3.38	33817

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.29 E-04	93.00	930000	3.09	30856
Other organic materials	Gamma Butyrolactone	96-48-0	4.73 E-05	7.00	70000	0.23	2323
Subtotal			6.76 E-04	100.00	1000000	3.32	33179

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.04 E-02**	**100.00**	**1000000**

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